



# **User's Guide**

# NHD-320240WG-BXTGH-VZ#-3VR LCM

### (Liquid Crystal Display Graphic Module) **RoHS Compliant**

NHD-Newhaven Display 320240-320 x 240 Dots WG-Graphic Type

B -Model serials number

Х-New IC rev. Т-LED, White

G-STN Positive, Gray Transflective, W.T,6:00 H-

VZ# -Negative voltage generator on board #: RoHS Compliant

3VR-3.3V supply, Frame Ground

For product support, contact

**Newhaven Display International** 2511 Technology Drive, #101

**Elgin, IL 60124** 

Tel: (847) 844-8795 Fax: (847) 844-8796

November 6, 2008

### **Contents**

- 1. Module classification information
- 2. Precautions in Use of LCM
- 3. General Specification
- 4. Absolute Maximum Ratings
- 5. Electrical Characteristics
- 6. Optical Characteristics
- 7. Interface Description
- 8. Contour Drawing & Block Diagram
- 9. Timing Characteristics
- 10. Reliability
- 11. Backlight Information
- 12. Inspection specification

### 1. Module Classification Information

NHD <u>320240</u> <u>WG - BX T G H -</u> VZ#-3VR 1 2 567 8

① Brand: NEWHAVEN DISPLAY INTERNATIONAL, LLC.

② Display Font: 320 \* 240 Dots

<sup>③</sup> Display Type: H→Character Type, G→Graphic Type

4 Model serials number: **B**. X: New IC rev.

⑤ Backlight Type: N→Without backlight A→LED, Amber

> B→EL, Blue green R→LED, Red

D→EL, Green O→LED, Orange

W→EL, White G→LED, Green

F→CCFL, White **T**→LED, White

Y→LED, Yellow Green S→LED, Bright White

© LCD Mode: B→TN Positive, Gray T→FSTN Negative

> N→TN Negative, M→STN Negative, Blue

**G**→STN Positive, Gray F→FSTN Positive

Y→STN Positive, Yellow Green

② LCD Polarizer A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Type/

Temperature

range/ View

direction

K→Transflective, W.T, 12:00 D→Reflective, N.T, 12:00

G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00

F→Transmissive, N.T,12:00 J→Reflective, W. T, 12:00

I→Transmissive, W. T, 6:00 B→Transflective, N.T,6:00

E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code VZ: Negative voltage generator on board

#: RoHS Compliant

**3VR**: 3.3V supply, Frame Ground

### 2. Precautions in Use of LCD Module

- (1) Avoid applying excessive shock to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD Module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please store in anti-static electricity container and clean environment.

### 3. General Specification

### NHD-320240WG-BXTGH-VZ#-3VR

ITEM	STANDARD VALUE	UNIT			
Number of dots	320x240	dots			
Outline dimension	160.0(W)x 109.0(H)x 13.0max(T)	mm			
View area	122.0(W)x 92.0(H)	mm			
Active area	115.18(W)x 86.38(H)	mm			
Dot size	0.34(W)x 0.34(H)	mm			
Dot pitch	0.36(W)x 0.36(H)	mm			
LCD type	STN-Gray (+), Transflect	ive			
View direction	6 o'clock				
Backlight	LED, White				

# 4. Absolute Maximum Ratings

ITEM	SYMBOL	MIN.	TYP.	MAX.	UNIT
Operating Temperature	$T_{\mathrm{OP}}$	-20	-	+70	ů
Storage Temperature	$T_{ST}$	-30	-	+80	°C
Input Voltage	V <sub>I</sub>	0	-	$V_{DD}$	V
Supply Voltage For Logic	$V_{ m DD}$	0	-	6.5	V
Supply Voltage For LCD	$V_{DD}$ - $V_{EE}$	0	-	32	V

# 5. Electrical Characteristics

ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Logic Voltage	$V_{DD}$ - $V_{SS}$	-	3.0	3.3	3.5	V
		Ta=-20°C	-	-	24.1	V
Supply Voltage For LCD	$ m V_{DD}$ - $ m V_{O}$	Ta=25°C	-	21.8	-	V
		Ta=+70°C	20.2	-	-	V
Input High Volt.	$V_{\mathrm{IH}}$	-	$0.5V_{DD}$	-	$V_{ m DD}$	V
Input Low Volt.	$V_{\mathrm{IL}}$	-	0	-	$0.2V_{\mathrm{DD}}$	V
Output High Volt.	V <sub>OH</sub>	-	V <sub>DD</sub> -0.4	-	-	V
Output Low Volt.	V <sub>OL</sub>	-	-	-	0.4	V
Supply Current	I <sub>DD</sub>	-	65.0	75.0	85.0	mA

# 6. Optical Characteristics

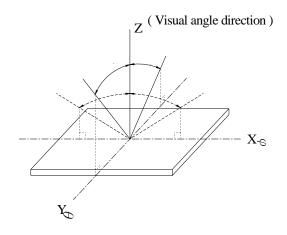
ITEM	SYMBAL	CONDITION	MIN	TYP	MAX	UNIT
	(V)θ	CR≧2	20	-	40	deg.
View Angle	(Н)ф	CR≧2	-30	-	30	deg.
Contrast Ratio	CR	-	-	3	-	-

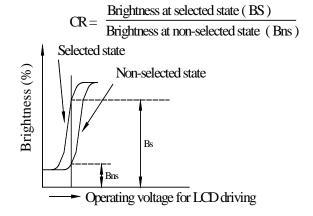
ITEM	SYMBAL	CONDITION	MIN	TYP	MAX	UNIT
	(V) θ	CR≧2	20		40	deg.
View Angle	(H) $\varphi$	CR≧2	-30	_	30	deg.
Contrast Ratio	CR	_	_	3	_	_
	T rise	_	_	200	300	ms
Response Time	T fall	_	_	150	200	ms

### 6.1 Definitions

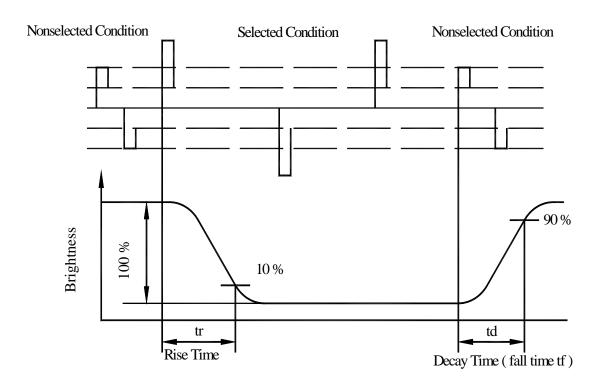
### **View Angles**

### **Contrast Ratio**





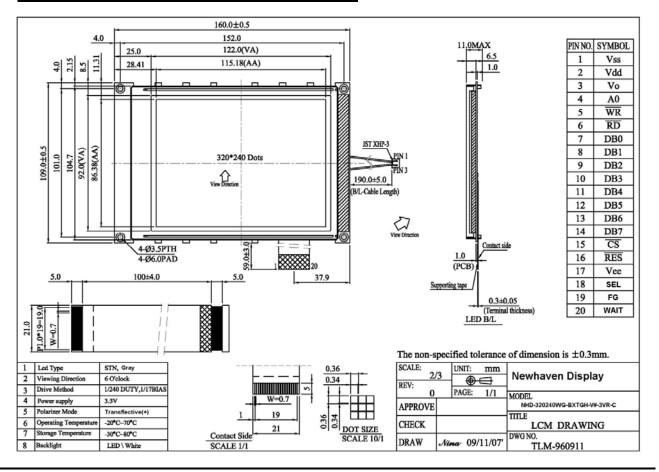
### **Response time**

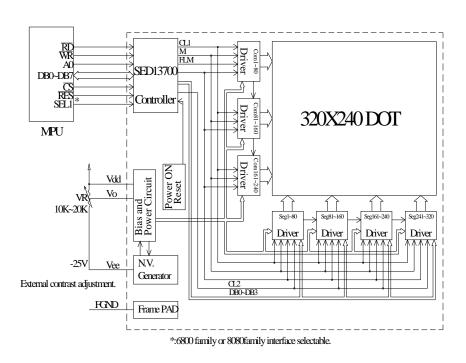


# 7. Interface Description

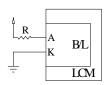
Pin No.	Symbol	Level	Description
1	$V_{SS}$	0V	Ground
2	$V_{\mathrm{DD}}$	3.3V	Power supply for Logic
3	$V_{O}$	(Variable)	Driving voltage for LCD
4	A0	H/L	RD=L WR=H ,A0=L :Data Read AO=H :Status read RD=H WR=L ,A0=L :Data Write AO=H :Command write
5	WR	H/L	8080 family: Write signal, 6800 family: R/W signal
6	RD	H/L	8080 family: Read signal, 6800 family: Enable clock
7~14	DB0~DB7	H/L	Data bus line
15	CS	H/L	Chip select ,Active L
16	RES	H/L	Controller reset signal, Active L
17	$V_{ee}$		Negative Voltage Output
18	SEL		8088 or 6800 interface selection 1:68 0: 80
19	FG		Frame Ground
20	WAIT		Check Busy

### 8. Contour Drawing & Block diagram





LEDB/L drive directly from A,K.



### 9. Timing Characteristics

For relative timing diagram please see the spec of S1D13700.

### 9.1 Differences Between SED1335 and S1D13700

- 1. S1D13700 almost can replace SED1335, and it can drive 240\*160 dots in 16 gray level, or 320\*240 dots in 4 gray level.
- 2. There are 2 Main differences and being described as below:
  - (1) . The Check Busy method of SED1335 is reading the D6 of STATUS resister.

#### Please

#### 14. STATUS FLAG

The SED1335 series has a single bit status flag. D6: X line standby

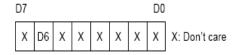


Figure 53. Status flag

The D6 status flag is HIGH for the TC/R-C/R cycles at the end of each line where the SED1335 series is not reading the display memory. The microprocessor may use this period to update display memory without affecting the display, however it is recommended that the display be turned off when refreshing the whole display.

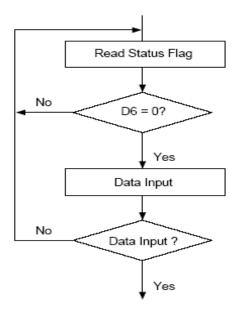
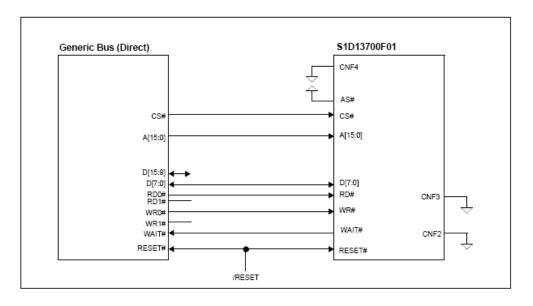


Figure 55. Flowchart for busy flag checking

The Check Busy method of S1D13700 is checking the "WAIT" pin directly.



(2) Owing to S1D13700 having 32K\*8 SRAM inside, so It doesn't need to set the bit "M1" in "SYSTEM SET". For S1D13700, we doesn't set M1 (bit1), the setting for SED 1335 is shown as

#### below:

#### 8.2.1.1. C

This control byte performs the following:

- 1. Resets the internal timing generator
- 2. Disables the display
- 3. Cancels sleep mode

Parameters following P1 are not needed if only canceling sleep mode.

#### 8.2.1.2. M0

Selects the internal or external character generator ROM. The internal character generator ROM contains 160,  $5\times7$  pixel characters, as shown in figure 70. These characters are fixed at fabrication by the metallization mask. The external character generator ROM, on the other hand, can contain up to 256 user-defined characters.

M0 = 0: Internal CG ROM M0 = 1: External CG ROM Note that if the CG ROM address space overlaps the display memory address space, that portion of the display memory cannot be written to.

#### 8.2.1.3. M1

Selects the memory configuration for user-definable characters. The CG RAM codes select one of the 64 codes shown in figure 46.

M1 = 0: No D6 correction.

The CG RAM1 and CG RAM2 address spaces are not contiguous, the CG RAM1 address space is treated as character generator RAM, and the CG RAM2 address space is treated as character generator ROM.

M1 = 1: D6 correction.

The CG RAM1 and CG RAM2 address spaces are contiguout and are both treated as character generator

#### The setting of S1D13700 will show as follow:

bit 1 Reserved

The default value for this bit is 0.

bit 0 Character Generator Select (M0)

This bit determines whether characters are generated by the internal character generator ROM (CGROM) or character generator RAM (CGRAM). The CGROM contains 160, 5x7 pixel characters which are fixed at fabrication. The CGRAM can contain up to 256 user-defined characters which are mapped at the CG Start Address (REG[1Ah] - REG[19h]). However, when the CGROM is used, the CGRAM can only contain up to 64, 8x8 pixel characters.

When this bit = 0, the internal CGROM is selected. When this bit = 1, the internal CGRAM is selected.

Note

If the CGRAM is used (includes CGRAM1 and CGRAM2), only 1 bpp is supported.

## 10.RELIABILITY

### Content of Reliability Test (wide temperature, -20°C~70°C)

	Environmental Test		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max  For 96hrs under no-load condition excluding the polarizer,  Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min  1 cycle	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude:  15mm  Vibration Frequency:  10~55Hz  One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

# 11. Backlight Information

(Ta=25°C)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	140	160	180	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	-
Reverse Voltage	VR	-	-	5	V	-
Luminous Intensity	IV	200	250	-	CD/M <sup>2</sup>	ILED=160mA
Wave Length	λр	-	-	-	nm	ILED=160mA
Life Time	-	-	50K	-	Hr.	ILED≦160mA
Color	White	1				1

Note: The LED of B/L is drive by current only, drive voltage is for reference only.

drive voltage can make driving current under safety area (current between minimum and maximum).

# 12. Inspection specification

NO	Item	Criterion					AQL
01	Electrical Testing	<ol> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character, dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 LCD viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Contrast defect.</li> </ol>					0.65
02	Black or white spots on LCD (display only)	<ul> <li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li> <li>2.2 Densely spaced: No more than two spots or lines within 3mm</li> </ul>					2.5
03	LCD black spots, white spots, contaminati on (non-display	3.1 Round type: $\Phi = (x + y)$ $X \longrightarrow X$ $Y \longrightarrow X$	)/2 ↓ Y	SIZE  Φ≦  0.10 < Φ3  0.20 < Φ3  0.25 < Φ	≦0.10 ≤0.20 ≤0.25	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are vis judge using bla specifications, to find, must cl specify direction	nck spot not easy heck in	Size Φ	.50 .00	Acceptable Q TY Accept no dense  3 2 0 3	2.5

NO	Item		Criterion		AQL	
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination				
06	Chipped	Symbols Define: x: Chip length y:	Chip width z: Ch Glass thickness a: LC	nip thickness CD side length	2.5	
		Z≦1/2t	Not over viewing area	x≦1/8a		
		1/2t < z≦2t	Not exceed 1/3k	x≦1/8a		
		⊙If there are 2 or more of the second of th	re chips, x is total len	gth of each chip.		
		z: Chip thickness	y: Chip width	x: Chip length		

Z≦1/2t	Not over viewing	x≦1/8a	
	area		
1/2t < z≦2t	Not exceed 1/3k	x≦1/8a	
⊙If there are 2 or mor	re chips, x is the total	length of each chip.	

NO	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:	
06	Glass cra ck	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5
		y: Chip width x: Chip length z: Chip thickness	
		y≦ L x≦1/8a 0 < z ≦ t	
		⊙If the chipped area touches the ITO terminal, over 2/3 of the	
		ITO must remain and be inspected according to electrode	
		terminal specifications.	
		⊙If the product will be heat sealed by the customer, the	
		alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack.	
		X	
		y: width x: length	
		y≦1/3L x ≦ a	

NO Item Criterion	AQL	
-------------------	-----	--

	1	Ţ	
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	<ul> <li>8.1 Illumination source flickers when lit.</li> <li>8.2 Spots or scratched that appear when lit must be judged.</li> <li>Using LCD spot, lines and contamination standards.</li> <li>8.3 Backlight doesn't light or color wrong.</li> </ul>	0.65 2.5 0.65
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>	2.5 0.65
10	РСВ, СОВ	<ul> <li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>10.2 COB seal surface may not have pinholes through to the IC.</li> <li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> <li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li> <li>10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> <li>10.9 The Scraping testing standard for Copper Coating of PCB</li> </ul>	2.5 2.5 0.65 2.5 2.5 0.65 2.5 2.5 2.5
11	Soldering	<ul> <li>11.1 No un-melted solder paste may be present on the PCB.</li> <li>11.2 No cold solder joints, missing solder connections, oxidation or icicle.</li> <li>11.3 No residue or solder balls on PCB.</li> <li>11.4 No short circuits in components on PCB.</li> </ul>	2.5 2.5 2.5 0.65